

DDR4 SDRAM PART NUMBERING

H 5 A N XX X X X X X - XX X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14

SK Hynix MEMORY

PRODUCT FAMILY

5 : DRAM

PRODUCT MODE

A : DDR4 SDRAM

POWER SUPPLY

N : VDD & VDDQ=1.2V

DENSITY & REFRESH

- 1G : 1Gb
- 2G : 2Gb
- 4G : 4Gb
- 8G : 8Gb
- AG : 16Gb
- BG : 32Gb

ORGANIZATION

- 4 : x4
- 8 : x8
- 6 : x16

DIE TYPE

- N : Non-TSV
- T : TSV

DIE GENERATION

- | | |
|---------|---------|
| M : 1st | D : 5th |
| A : 2nd | E : 6th |
| B : 3rd | F : 7th |
| C : 4th | G : 8th |

OPERATING TEMPERATURE & POWER CONSUMPTION

- C : Commercial Temp(0°C ~ 85°C) & Normal Power
- R : Commercial Temp(0°C ~ 85°C) & Reduced IDD6

SPEED(tCL-tRCD-tRP)

- TF : DDR4-2133 15-15-15
- UH : DDR4-2400 17-17-17
- UL : DDR4-2400 20-18-18
- VK : DDR4-2666 19-19-19
- VN : DDR4-2666 22-19-19
- WM : DDR4-2933 21-21-21
- XN : DDR4-3200 22-22-22

PACKAGE MATERIAL

- R : Lead Free & Halogen Free (ROHS compliant)

PACKAGE TYPE

- F : FBGA SDP
- J : Flipchip SDP
- M : FBGA DDP
- P : Flipchip Planar DDP
- 2 : TSV 2 high stack
- 4 : TSV 4 high stack